

Effisus 2Bond DS

Substrate Preparation

1

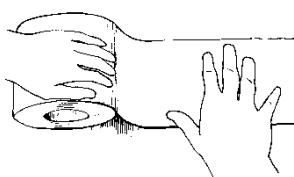


All substrates should be dry. Please clean all non-absorptive, smooth substrates using the Effisus Setup PR Cleaner.

Remove any loose material from absorptive, porous substrates, such as concrete, and subcoat these substrates with the Effisus Coat EP Primer. Allow the primer to flash off. Bonding operations can not be carried out at temperatures below -29°C. For temperatures between 4.5°C and -29°C always subcoat the substrates with Effisus Coat EP Primer.

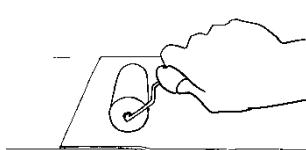
Connecting Operations

2



To apply the Effisus 2Bond DS Tape, remove one side of the release liner and apply to the surface to be protected or bonded. Rub or roll with pressure using your hand or a steel roller to activate bonding process. Remove the second release liner and apply second surface to tape, apply pressure.

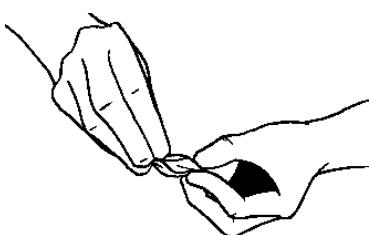
3



Seams between Effisus 2Bond DS Tapes should have a minimum overlap of 100mm.

Adhere the top Effisus 2Bond DS Tape over the bottom Effisus 2Bond DS Tape. Rub or roll with pressure using a steel roller to activate bonding process.

4



Effisus 2Bond DS Tape also can be used as a putty. Remove both release liners and roll into a rope. Place Effisus 2Bond DS over the gap and mold to the seal the opening.

Effisus 2Bond DS Tape is self-sealing. It can be used to seal penetrating screws or nail shanks.

Putty